

F tL tL tL raL tL a a
P. Da^a

ti/ra a a . Tr ti/ ti/ al a ti/ r -
a, ti/ . I,
S_i Pb a , Pb ti/ a, ti/ al ti/ ti/ a, ti/ -
al (165 °C). ti/ ti/ ti/ ti/ -
ti/ bt/al ti/ ti/ ti/ -
a, b ti/ ti/ a, Pb al , a, S_i
ti/ ti/ ti/ a a, b
Pb . I, S_i A , S_i ti/ a, ti/ . ti/
ti/ ti/ a, S_i al , A₃S_i ti/ ti/ a -
ti/ . E ti/ S_i a a ti/ al ti/
ti/ a, a, a ti/ al a .
C a, ti/ a, UBM WLP ti/ ti/ ti/ a , ti/ WLP
ti/ ti/ , ti/ a , al ti/ ti/ al , ti/
I, a UBM al , , ti/ al ti/ al
ti/ al a , b , ti/ ti/ a a ti/ ti/ UBM
a , W a ti/ WLP ti/ ti/ , , ti/ -
al a , b PCB .



Fig. 8. (a) FEA simulation of the package showing temperature distribution. (b) Schematic diagram of the package showing the locations of sensors A and B, and the positions of the solder joints (1, 2, 3, 4).

The finite element analysis (FEA) simulation of the package is shown in Fig. 8(a). The simulation shows the temperature distribution in the package and the PCB. The maximum temperature is 170 °C, which occurs at the solder joints. The minimum temperature is 25 °C, which occurs at the ambient. The schematic diagram of the package is shown in Fig. 8(b). The package is mounted on a PCB. The locations of sensors A and B are shown. The positions of the solder joints (1, 2, 3, 4) are also shown.

Table 1
Electrical and thermal parameters [3,9–14].

Parameter	Unit	Value
E_A	V	0.8
Z		23
D_0	$2/\mu\text{m}^2$	0.027
Q	V	0.0094
ρ_0	Ω	13.3–8
α	1/K	2.8–3
Ω	$3/\mu\text{m}^2$	2.72–29

Table 2
Material properties of the package.

Material	Material properties
	S (J/K) Thermal conductivity (W/K) E (GPa) α ($10^{-6}/\text{K}$)
PCB	1.7 1.10
Solder (SAC)	219 57.26 13.3 8(1+2) 3 Δ T
S	150 4.4
Copper	385.2 393 1.58 8(1+4.3) 3 Δ T
Epoxy	2185 1.2 1.17

The material properties of the package are listed in Table 2. The material properties are: S (J/K), Thermal conductivity (W/K), E (GPa), and α ($10^{-6}/\text{K}$).

5. Results

5.1. Current density

The current density distribution in the package is shown in Fig. 9. The current density is highest at the solder joints and lowest at the ambient. The schematic diagram of the package is shown in Fig. 2. The locations of the solder joints (1, 2, 3, 4) are shown. The current density distribution is shown in Fig. 9(a). The current density is highest at the solder joints and lowest at the ambient. The schematic diagram of the package is shown in Fig. 2. The locations of the solder joints (1, 2, 3, 4) are shown.

0.139 9 A/ ².
F . 10
b -b S
b a b . T a b a
F . 10

5.4. Divergence analysis

$\nabla \cdot \mathbf{a} = \frac{\partial a_i}{\partial x_i} = \frac{\partial}{\partial x_i} (a_i) = \frac{\partial}{\partial x_i} (a_i)$
 $\frac{\partial}{\partial x_i} (a_i) = \frac{\partial a_i}{\partial x_i} = \frac{\partial a_i}{\partial x_i}$
 $\frac{\partial a_i}{\partial x_i} = \frac{\partial a_i}{\partial x_i} = \frac{\partial a_i}{\partial x_i}$

E. J. ... , Ma 31 J 3, FL, USA, 2005.

- [11] Na JW, R F, T KN. E. J. ... Pb ... L 2006;99:023520.
- [12] La YS, C KM, Ka CL. E. J. ... S₃₇Pb a S_{3A} 1.5C /S_{3A} 0.5C ... T/N(V)/C ... M ... R ab 2006;48:811 24.